

Hongbo Qin

List of Publications by Year in descending order

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22
papers

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citations

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docs citations

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454
citing authors

#	ARTICLE	IF	CITATIONS
1	Influence of phase inhomogeneity on the mechanical behavior of microscale Cu/Sn ⁵⁸ Bi/Cu solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 244.	1.1	0
2	Influence of Microstructure Evolution on the Current Density and Temperature Gradient of Line-Type Cu/Sn ⁵⁸ Bi/Cu Microscale Solder Joints Under Current Stressing. <i>Journal of Electronic Materials</i> , 2022, 51, 1116-1127.	1.0	1
3	Weakened strengthening effect in the Ag added microscale SnBi joints under current stressing. <i>Materials Letters</i> , 2022, 312, 131677.	1.3	4
4	Shear performance of microscale ball grid array structure Cu(Ni)/Sn ^{3.0} Ag ^{0.5} Cu/Cu(Ni) solder joints at low temperatures. <i>Materials Today Communications</i> , 2022, 30, 103149.	0.9	3
5	First-Principles Study on the Elastic Mechanical Properties and Anisotropies of Gold ⁴ Copper Intermetallic Compounds. <i>Metals</i> , 2022, 12, 959.	1.0	9
6	Crystallographic Characteristic Effect of Cu Substrate on Serrated Cathode Dissolution in Cu/Sn ^{3.0} Ag ^{0.5} Cu/Cu Solder Joints during Electromigration. <i>Materials</i> , 2021, 14, 2486.	1.3	5
7	Adsorption behavior of HCOOH on the crystal surfaces of Cu(111) and (100)., 2021, , .		0
8	Size effect on tensile performance of microscale Cu/Sn ^{3.0} Ag ^{0.5} Cu/Cu joints at low temperatures. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 28454-28467.	1.1	5
9	The Mechanical Properties and Elastic Anisotropy of β -Cu ₆ Sn ₅ and Cu ₃ Sn Intermetallic Compounds. <i>Crystals</i> , 2021, 11, 1562.	1.0	4
10	Influence of microstructure inhomogeneity on the current density and temperature gradient in microscale line-type Sn ⁵⁸ Bi solder joints under current stressing. <i>Microelectronics Reliability</i> , 2020, 115, 113995.	0.9	11
11	Stress Concentration Induced by the Crystal Orientation in the Transient-Liquid-Phase Bonded Joint of Single-Crystalline Ni ₃ Al. <i>Materials</i> , 2019, 12, 2765.	1.3	5
12	Asymmetric Long-Range Surface Plasmon Polariton Waveguides for Sensing Applications. <i>IEEE Photonics Journal</i> , 2019, 11, 1-9.	1.0	1
13	First Principles Study of Gas Molecules Adsorption on Monolayered β -SnSe. <i>Coatings</i> , 2019, 9, 390.	1.2	11
14	Influence of Phase Inhomogeneity on Electromigration Behavior in Cu/Sn-58Bi/Cu Solder Joint. <i>Journal of Electronic Materials</i> , 2019, 48, 3410-3414.	1.0	6
15	First-Principles Investigation of the Adsorption Behaviors of CH ₂ O on BN, AlN, GaN, InN, BP, and P Monolayers. <i>Materials</i> , 2019, 12, 676.	1.3	27
16	A Theoretical Review on Interfacial Thermal Transport at the Nanoscale. <i>Small</i> , 2018, 14, 1702769.	5.2	83
17	First-principles investigation of adsorption behaviors of small molecules on penta-graphene. <i>Nanoscale Research Letters</i> , 2018, 13, 264.	3.1	51
18	Influence of Pressure on the Mechanical and Electronic Properties of Wurtzite and Zinc-Blende GaN Crystals. <i>Crystals</i> , 2018, 8, 428.	1.0	2

#	ARTICLE	IF	CITATIONS
19	Gas sensing properties of two-dimensional penta-BP5: A first-principle study. Chemical Physics Letters, 2018, 706, 355-359.	1.2	16
20	The Mechanical Properties and Elastic Anisotropies of Cubic Ni3Al from First Principles Calculations. Crystals, 2018, 8, 307.	1.0	88
21	Mechanical, Thermodynamic and Electronic Properties of Wurtzite and Zinc-Blende GaN Crystals. Materials, 2017, 10, 1419.	1.3	52
22	Influence of microstructure inhomogeneity on the electromigration behavior of flip chip solder joints. , 2016, , .		0